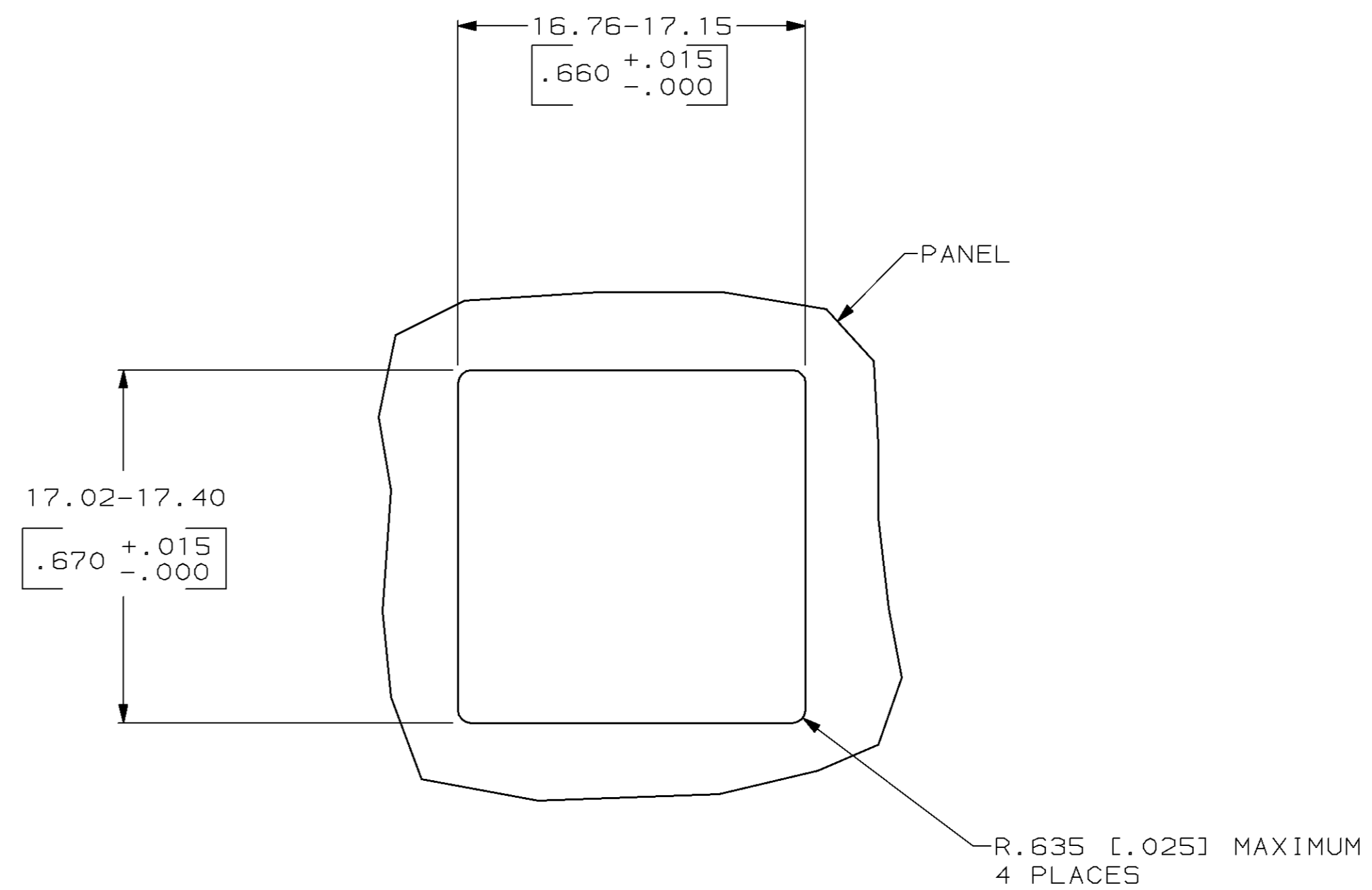
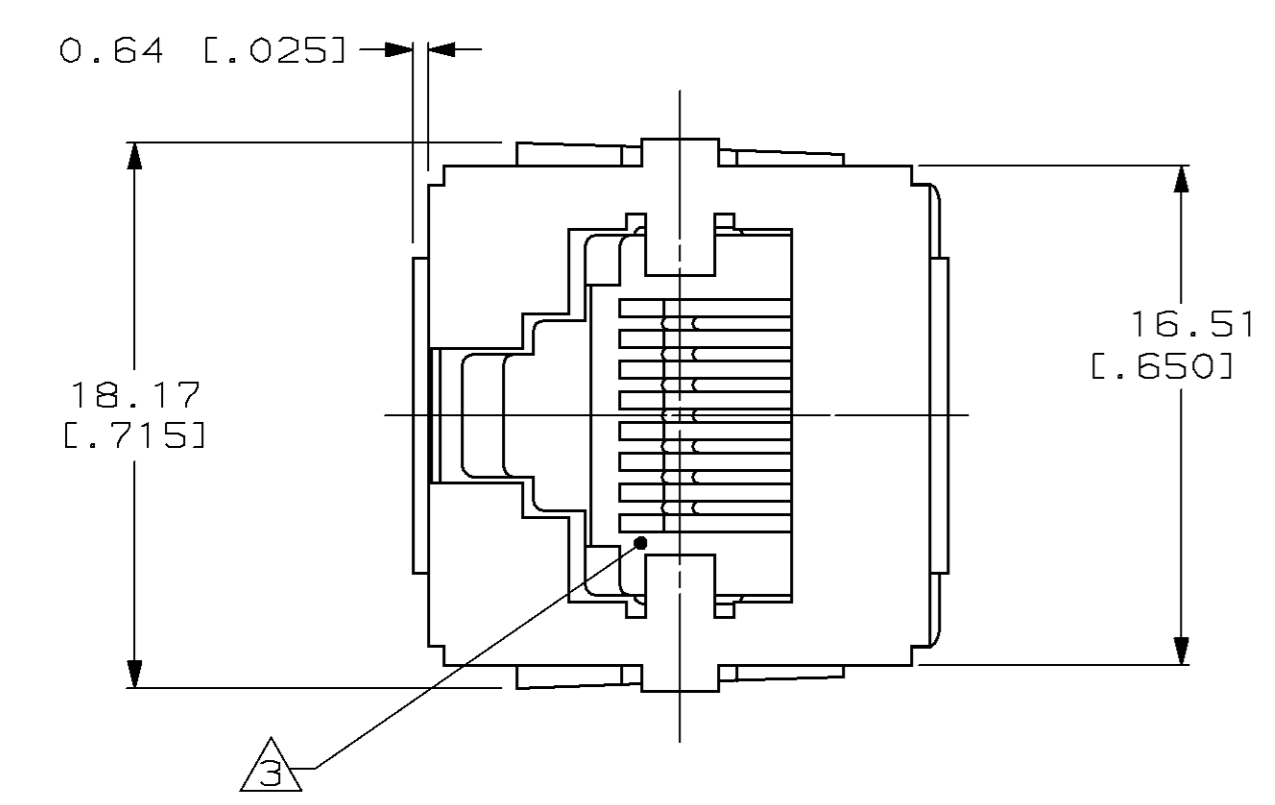
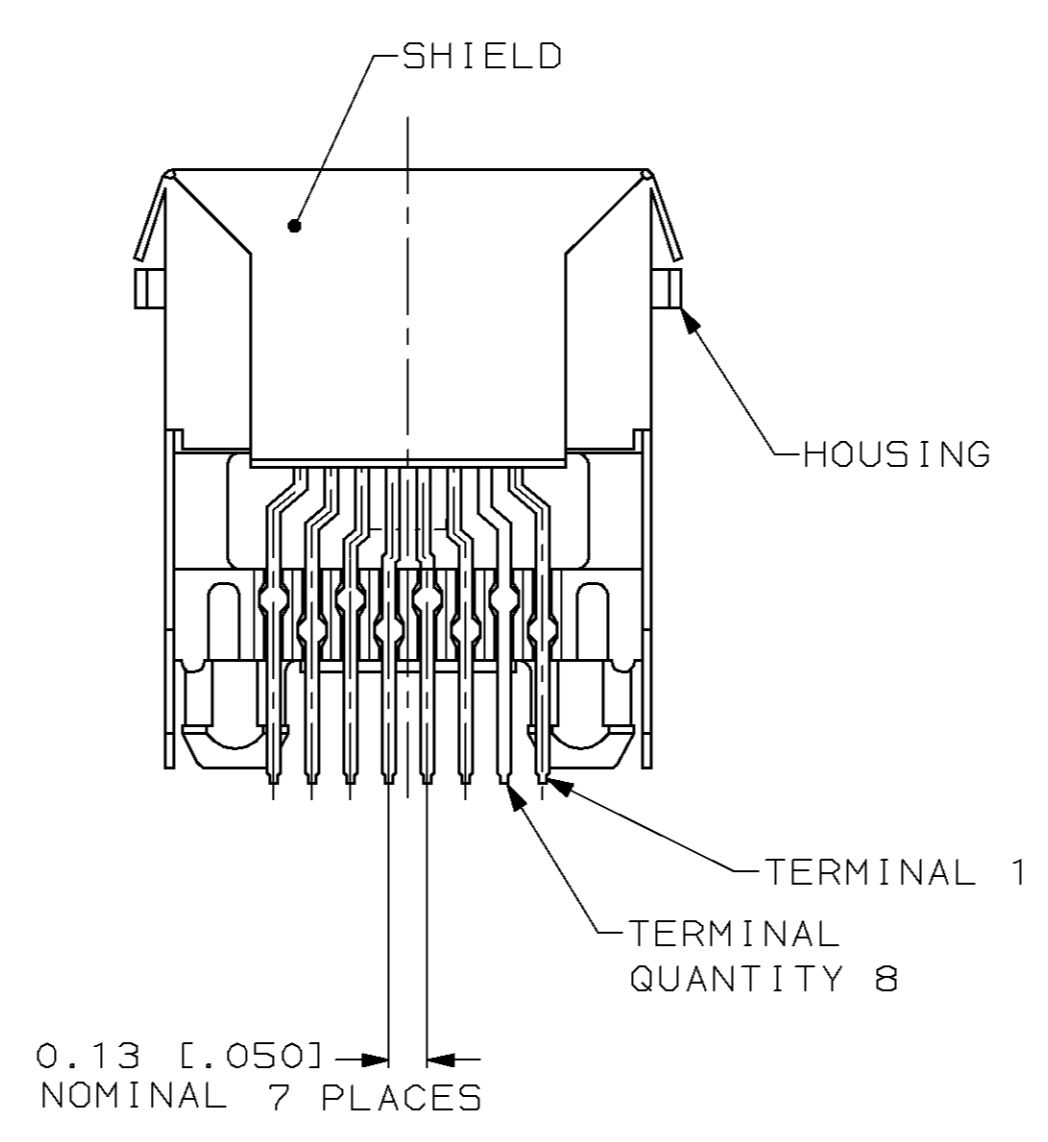
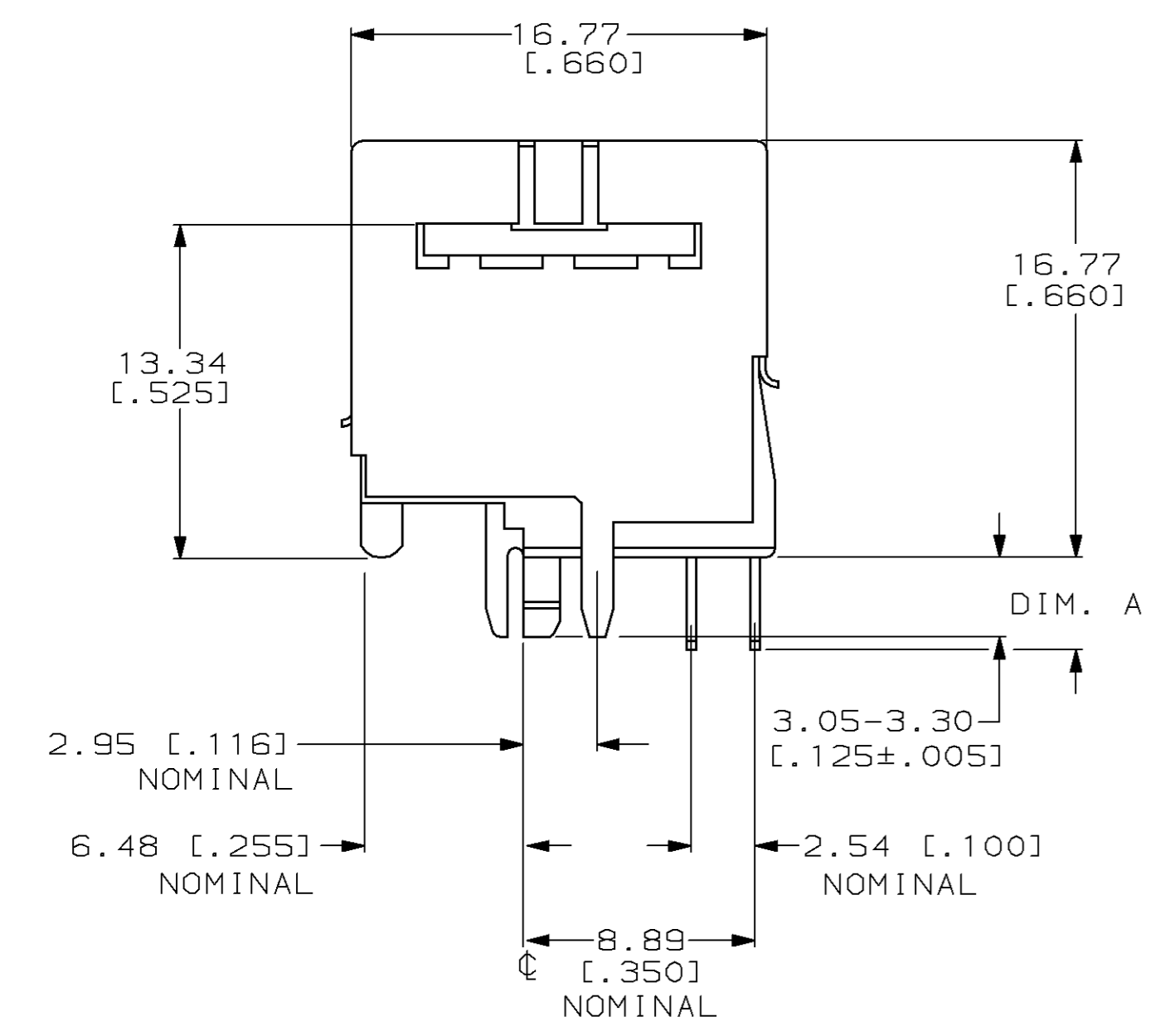


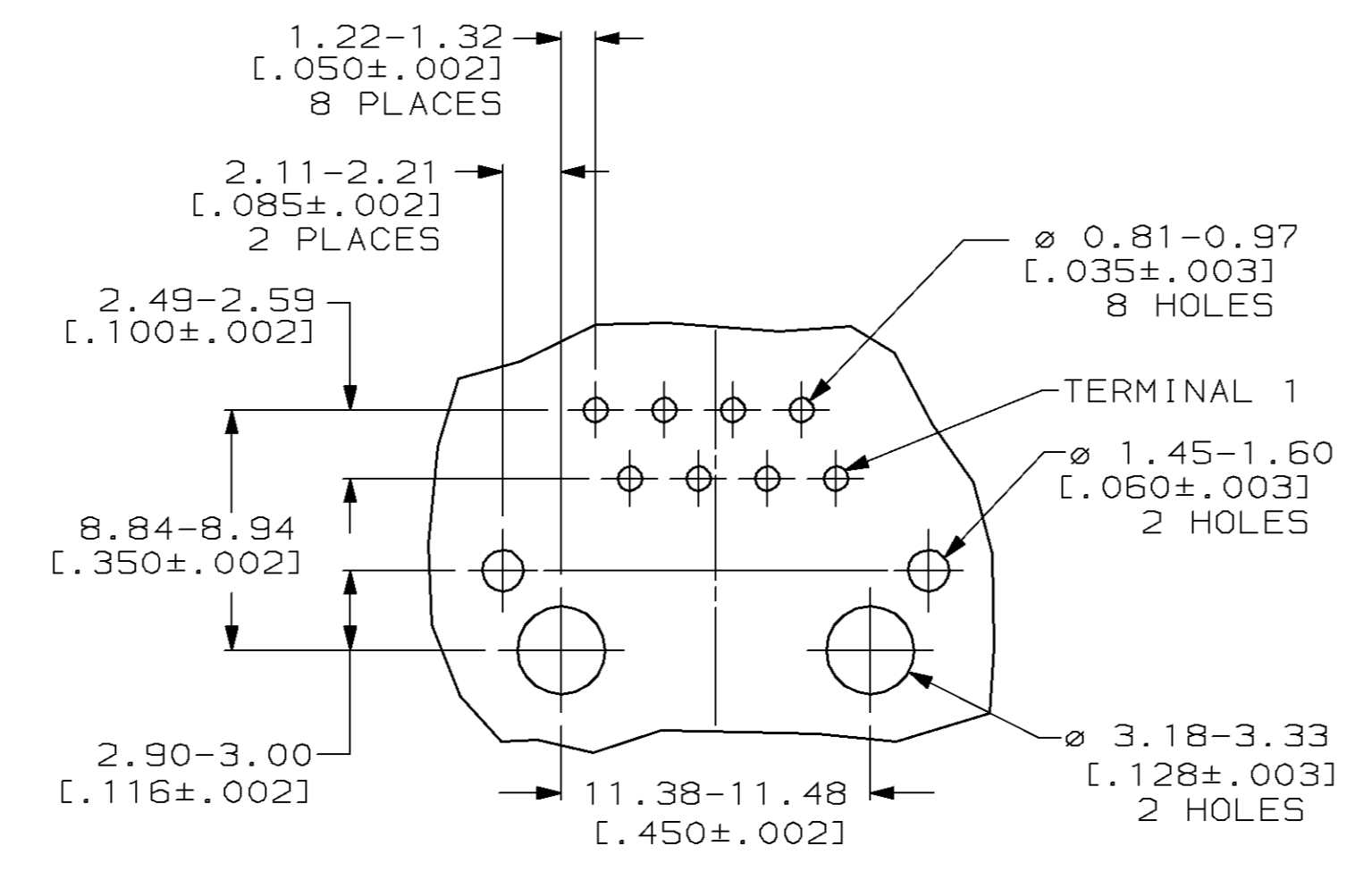
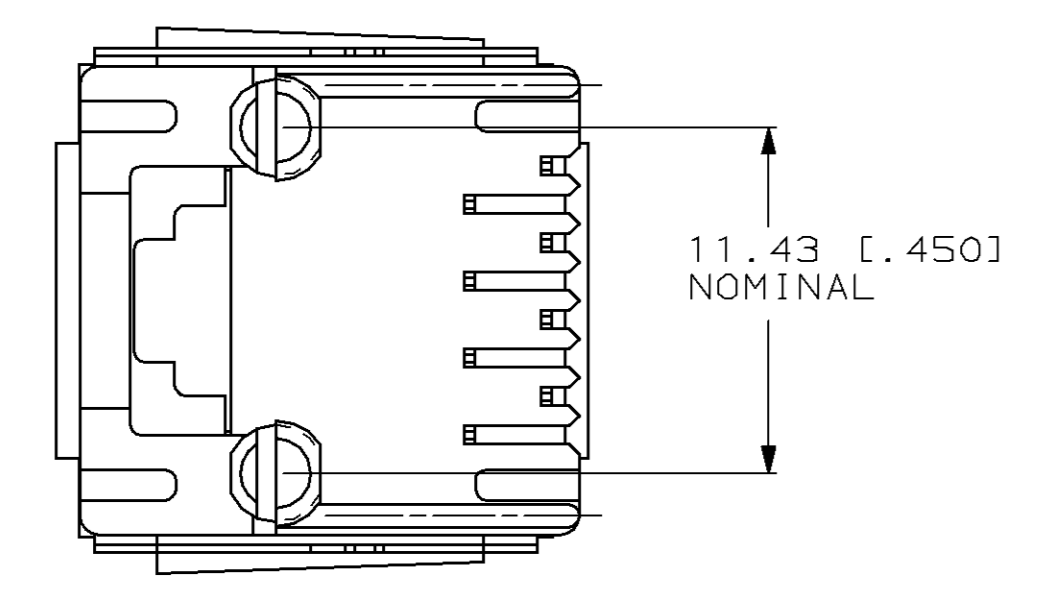
LOC		DIST		P		F		ZONE		LTR		REVISIONS		
AA	22											DESCRIPTION	DATE	APPD
												REV; EC 0210-0231-96	6-5-96	LM/UTA



- 1 DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.
- 2 MATERIAL: HOUSING- POLYESTER MOLDING COMPOUND, BLACK.  
 TERMINALS- 0.350 [0.0138] THICK PHOS BRONZE PLATED WITH 1.27µm [0.00050] MINIMUM THICK GOLD IN LOCALIZED AREA AND 3.81µm [0.000150] MINIMUM THICK TIN-LEAD IN SOLDER AREA OVER 1.27µm [0.00050] MINIMUM THICK NICKEL UNDERPLATE.  
 SHIELD- COPPER ZINC ALLOY PLATED WITH 2.03µm [0.00080] MINIMUM THICK TIN-LEAD OVER 2.54µm [0.00100] MINIMUM THICK COPPER UNDERPLATE.
- 3 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLITIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.



SUGGESTED PANEL CUTOUT



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT  
 NONCOMPONENT SIDE SHOWN

2.79-3.30 [0.120±0.010]	557969-2
2.92-3.94 [0.135±0.020]	557969-1
DIM. A	PART NO

DO NOT SCALE PRINT. UNLESS SPECIFIED DIMENSIONS IN mm [INCHES] TOLERANCES ON:	DR 6-16-93 B. SIMPSON	<b>AMP</b> AMP Incorporated Harrisburg, PA 17105-3608
2 PLC DEC ± -	CHK 6-24-93 B. FOX	
3 PLC DEC ± -	APPD 6-24-93 J. TONEY	NAME MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, WITH PANEL STOPS, PANEL & PCB GROUNDS
ANGLES ± -	APPD 6-24-93 H. MCGRATH	PRODUCT SPEC 108-1163
MATERIAL	APPLICATION SPEC 114-2048	SIZE D 00779
FINISH	WEIGHT -	CAGE CODE 00779
		DRAWING NO C-557969
		SCALE 4:1
		SHEET 1 OF 1

THIS DRAWING IS A CONTROLLED DOCUMENT FOR AMP INCORPORATED. IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.